



PRODUCT/ PROCESS CHANGE NOTICE

Number: 1308-1
Date: 8/27/13
From: Joseph Bloch
ECO#: 8173
ECO Ref.: (Class: 3 Notification)

Effective Date: TBD

Reason for Change: Component change to the FR4 circuit board with the addition of thermal insulation to enhance performance.

Change Category: Change in Existing Product Design/Component Parts

Executive Summary: Component change (PCB) to enhance thermal performance.

Products Affected: DOC Product Family

Effect on Product Performance: There will be enhanced thermal performance through the modification of the FR4 circuit board. The modification is to provide an air pocket, or thermal gap, between the bottom of our package and the customer board. This additional feature allows the OCXO to maintain its thermal stability under a wider range of customer board layout configurations. Overall package height will increase slightly (0.312" Maximum).

Change Impact:

Product model will remain the same however version numbers will change as necessary.

CHANGEOVER PROCESS: By mutual agreement between Connor Winfield and the customer.

Test SAMPLES Available: X Yes No

Test DATA Available: X Yes No

Connor-Winfield Contact Person: Joseph T. Bloch, Q.A. Manager Telephone Extension: 6106

Please acknowledge this communication with your approval if the above items are satisfactory.

CUSTOMER RESPONSE

This PCN requires customer notification. Use this form if necessary to respond and direct to the attention of the contact person at Connor-Winfield Corporation.

If Unacceptable, Explain:

Customer Contact

Telephone:

Email
